Supporting Information

Dielectric Behavior of Self-Assembled Monolayers on Conducting Metal Oxides

Oktay Yildirim,^{*a,b*} Michiel G. Maas,^{*a*} Peter J. de Veen,^{*a*} Minh D. Nguyen,^{*a*} David N. Reinhoudt,^{*b*} Dave H. A. Blank,^{*a*} Guus Rijnders,^{*a**} and Jurriaan Huskens^{*b**}

MESA+ Institute for Nanotechnology, University of Twente, P.O. Box 217, 7500 AE, Enschede, The Netherlands. ^aInorganic Materials Science, Fax: +31 53 4893595; Tel: +31 53 4892618; E-mail: a.j.h.m.rijnders@utwente.nl ^b Molecular Nanofabrication Group, Fax: +31 53 4894645; Tel: +31 53 4892995; E-mail: j.huskens@utwente.nl



Figure S1. Chemical structure of tetradecylphosphoric acid (TDP).

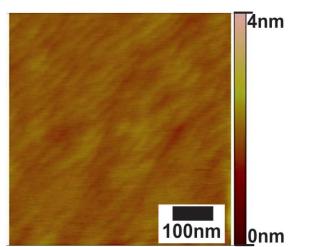


Figure S2. Contact mode AFM height image of a blank Nb-STO surface.

More detailed characterization of TDP SAMs on NbSTO has been reported before.^[1]

Figure S3 shows the elemental spectra after electrodeposition of Cu on the region of a Ptpatterned TDP SAM-covered Nb-STO sample as shown in Figures 2c,d and 3b. According to the XPS result, atomic concentrations of the elements in the region are: 68.5 % C, 26% O, 1.5% Cu and 4% Pt.

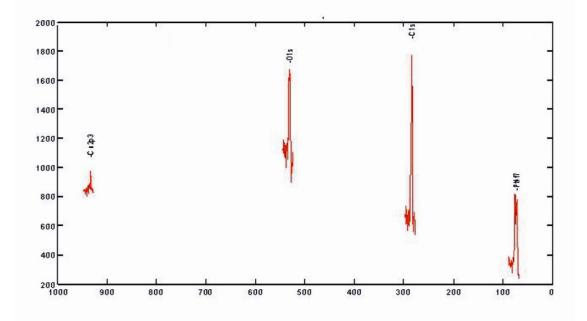


Figure S3. Elemental spectra of the area where electrodeposited Cu was seen on the Pt patterns deposited by PLD on TDP-covered Nb-STO.

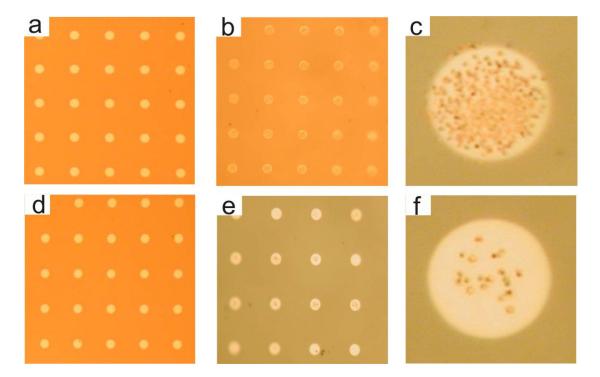


Figure S4. Optical images of Pt top contacts of (a) bare Nb-STO after stencil deposition by PLD with conditions for harsh landing. (b, c) Same sample after electrochemical Cu deposition, with the zoom-in to a region where Cu growth was seen (c). Optical images of Pt (d) top contacts of TDP SAM-modified Nb-STO after stencil deposition by PLD with conditions for harsh landing. (e,f) Same sample after electrochemical Cu deposition, with the zoom-in to a region where Cu growth was seen (f).

References

1. O. Yildirim, M. D. Yilmaz, D. N. Reinhoudt, D. H. A. Blank, G. Rijnders, J. Huskens, *Langmuir* **2011**, *27*, 9890-9894.